

ABSTRACT OF THE DISCLOSURE

In order to provide a magnetic loss material exhibiting outstanding high-frequency magnetic loss characteristics extremely effective in eliminating high-frequency transmission noise from very densely integrated electronic microcircuits such as semiconductor integrated circumference devices, together with a manufacturing method therefor and a high-frequency current suppression body wherein such is used, the present invention is a high-frequency current suppression body having a sheet shape comprising an adhesive layer or a pressure-sensitive adhesive layer (23) on at least one surface of a magnetic thin film (19). This magnetic thin film is a magnetic loss material consisting of M-X-Y, where M is at least one of Fe, Co, and Ni, X is at least one element other than M or Y, and Y is at least one of F, N, and O. The maximum value μ''_{\max} of the loss factor μ'' of the magnetic loss material exists in a frequency range of 100 MHz to 10 GHz. A relative bandwidth bwr is not greater than 200% where the relative bandwidth bwr is obtained by extracting a frequency bandwidth between two frequencies at which the value of μ'' is 50% of the maximum μ''_{\max} and normalizing the frequency bandwidth at the center frequency thereof.